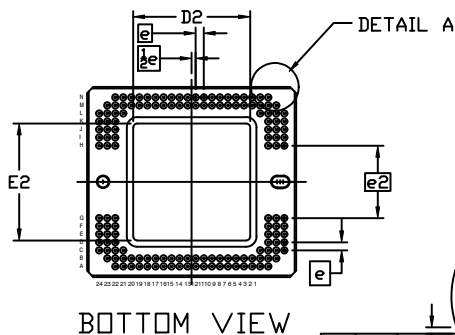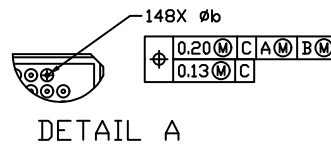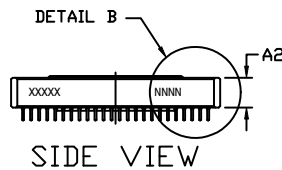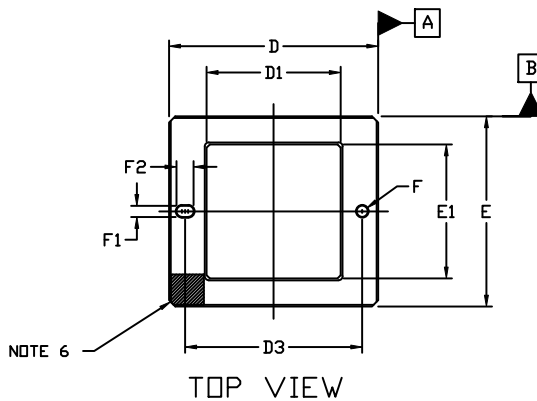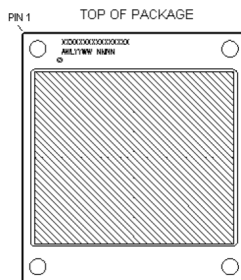**CPGA148, 33x30**
CASE 107FK
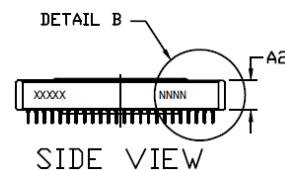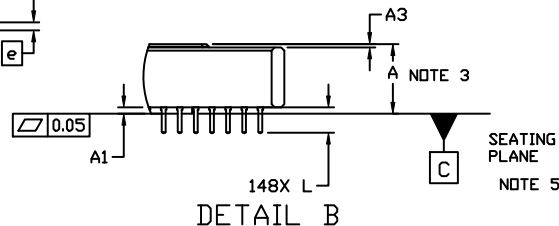ISSUE O

DATE 04 APR 2018

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A INCLUDES THE PACKAGE BODY, GLASS, AND HEATSINK.
4. DIMENSIONS D AND E DO NOT INCLUDE PROTRUSIONS. SUCH PROTRUSIONS SHALL NOT EXTEND MORE THAN 0.08 ON ANY SIDE. CORNERS AND EDGES OF THE PACKAGE MAY HAVE CHAMFERS.
5. THE SEATING PLANE IS DEFINED BY THE OUTER HEATSINK SURFACE.
6. PIN A1 IDENTIFICATION WILL BE IN THIS AREA. ID TYPE MAY CONSIST OF NOTCHES, METALLIZED MARKINGS, OR OTHER FEATURES.



TOP VIEW

DETAIL B

SIDE VIEW

DETAIL A

BOTTOM VIEW

DETAIL B

| DIM | MILLIMETERS | | |
|-----|------|------|------|
| | MIN. | NOM. | MAX. |
| A | 5.49 REF | | |
| A1 | 0.45 | 0.50 | 0.55 |
| A2 | 4.24 | 4.72 | 5.20 |
| A3 | 0.27 REF | | |
| b | 0.25 | 0.30 | 0.35 |
| D | 32.67 | 33.00 | 33.33 |
| D1 | 21.05 | 21.13 | 21.21 |
| D2 | 18.34 | 18.44 | 18.54 |
| D3 | 27.66 | 27.94 | 28.22 |
| E | 29.70 | 30.00 | 30.30 |
| E1 | 21.05 | 21.13 | 21.21 |
| E2 | 18.34 | 18.44 | 18.54 |
| e | 1.27 BSC | | |
| e2 | 11.30 | 11.43 | 11.56 |
| F | 1.65 | 1.75 | 1.85 |
| F1 | 1.65 | 1.75 | 1.85 |
| F2 | 2.57 | 2.72 | 2.87 |
| L | 1.80 | 2.00 | 2.20 |

**GENERIC MARKING DIAGRAM**

TOP OF PACKAGE

PIN 1

XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
NNNN = Serial Number

XXXX = Specific Device Code
NNNN = Serial Number

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|---|---|---|---|
| DESCRIPTION: | CPGA148, 33x30 | | PAGE 1 OF 1 |